

material also having trench features therein; and electrically conductive material deposited in said trench features forming electrically conductive circuit lines being substantially flush with said second top surface of said second dielectric layer of polymeric material, wherein said polymeric material is at least one member selected from the group consisting of thermoplastic resin and thermosetting resin, and further including a third dielectric layer of polymeric material located on said electrically conductive circuit lines.

Please add the following new claims.

32. (Added) An electronic structure comprising:

a first dielectric layer of polymeric material having a first top surface;
a second dielectric layer of polymeric material on said first top surface of said first dielectric layer of polymeric material, having a second top surface, said second layer of polymeric material also having trench features therein; and electrically conductive metal deposited in said trench features forming electrically conductive circuit lines being substantially flush with said second top surface of said second dielectric layer of polymeric material, wherein said polymeric material is at least one member selected from the group consisting of thermoplastic resin and thermosetting resin, and wherein said first dielectric layer of polymeric material is a different material than said second dielectric layer of polymeric material.

33 (Added). The electronic structure of claim 32 further including a third dielectric layer of dielectric polymeric material located on said conductive circuit lines.

34. (Added) The electronic structure of claim 32 wherein said plated metal is copper.

35 (Added). The electronic structure of claim 32 wherein the circuit lines are about 0.5 to about 1 mil wide, about 0.5 to about 2 mils apart and up to about 20 microns thick.